5G智能物联网

开发套件硬件搭建介绍

广和通大学计划项目组

2023Q2



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SC171开发套件组成部分

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开发板:

ADP+EVKB

包装配件:

天线*7

电源适配器*1

TYPE-C数据线*1

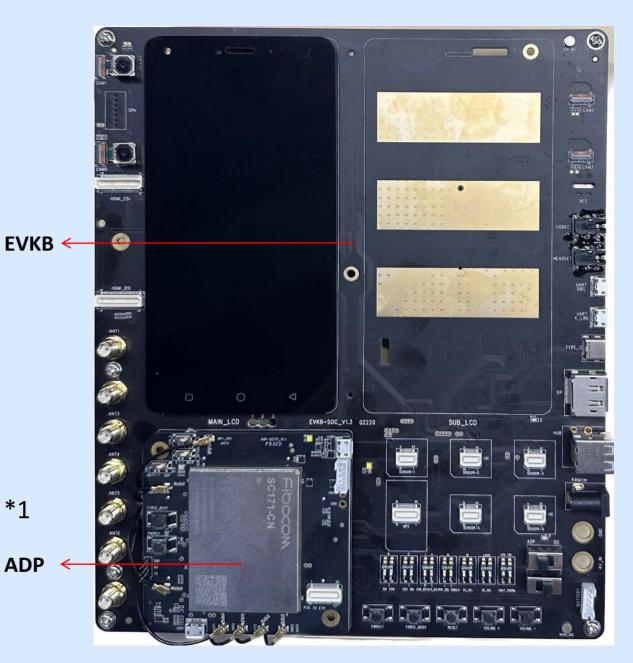
光感和近距离传感器*1

加速度和陀螺仪传感器*1

地磁传感器*1

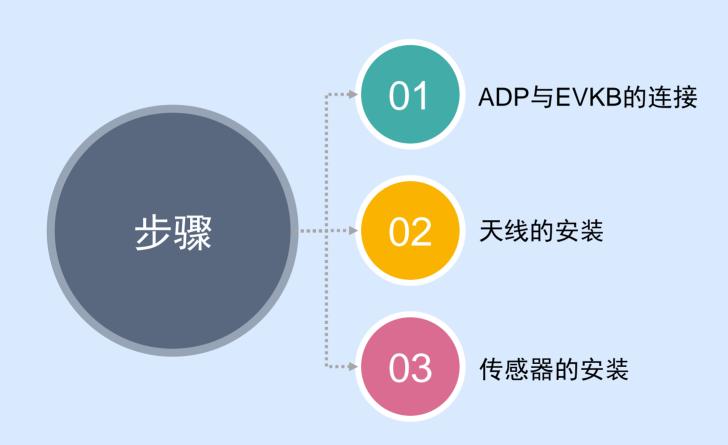
加速度和陀螺仪传感器+霍尔传感器*1

震动马达*1



SC171开发套件硬件搭建实操

SC171开发套件硬件搭建实操





完美无线体验

广和通致力于将可靠、便捷、安全、智能的无线 通信解决方案普及至每一个物联网应用场景,为 用户带来完美无线体验,丰富智慧生活。

We are committed to enabling industries with reliable, accessible, secure, and intelligent IoT wireless solutions and wireless module products to maximize their value, providing a perfect wireless experience to people and enriching smart life of the whole society.

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